### **General Description**

The SJ30N019 uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a wide variety of applications.

#### **Features**

- Low Gate Charge
- 100% UIS Tested, 100% DVDS Tested
- High Power and current handing capability
- Lead free product is acquired

### **Application**

- Load switch
- PWM applications
- Power management

### **Key Performance Parametes**

Parameter	Value	Unit
V <sub>DS</sub>	30	V
R <sub>DS(ON)_TYP</sub>	2.2	mΩ
I <sub>D</sub>	155	Α
Q <sub>G</sub>	68	nC



### **Package Marking and Ordering Information**

Device/Ordering Code	Marking	Package	Packing	Reel Size	Tape width	Quantity
SJ30N019	SJ30N019	TO-220	Tube	1	1	1000 Pcs

### Table 1. Absolute Maximum Ratings (T<sub>c</sub>=25℃ unless otherwise noted)

Symbol	Parameter	Limit	Unit
V <sub>DS</sub>	V <sub>DS</sub> Drain-Source Voltage (V <sub>GS</sub> =0V)		V
V <sub>G</sub> S	V <sub>GS</sub> Gate-Source Voltage (V <sub>DS</sub> =0V)		V
I-	Drain Current-Continuous(Tc=25°ℂ)	155	Α
I <sub>D</sub>	Drain Current-Continuous(Tc=100℃)	95	Α
I <sub>DM</sub> (pluse)	Drain Current-Continuous@ Current-Pulsed (Note 1)	620	Α
В	Maximum Power Dissipation(Tc=25°ℂ)	104	W
P <sub>D</sub>	Maximum Power Dissipation(T <sub>C</sub> =100°C)	42	W
E <sub>AS</sub>	Avalanche energy (Note 2)	441	mJ
TJ, TSTG	Operating Junction and Storage Temperature Range	-55 To 150	°C

#### Table 2. Thermal Characteristic

Symbol	Parameter	Тур	Max	Unit
R <sub>θ</sub> JC	Thermal Resistance, Junction-to-Case		1.2	°C/W



Table 3. Electrical Characteristics (T<sub>J</sub>=25℃ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
On/Off States	•					
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	30			V
	7 0 1 1/1 5 : 0 1	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V T <sub>J</sub> =25℃			1	μΑ
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V T <sub>J</sub> =125℃			100	μΑ
Igss	Gate-Body Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V			±100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250µA	1.0		2.5	V
<b>G</b> FS	Forward Transconductance	V <sub>DS</sub> =5V, I <sub>D</sub> =20A		45		S
	D : 0 0 0 1 1 D : 1	V <sub>GS</sub> =10V, I <sub>D</sub> =20A T <sub>J</sub> =25°C		2.2	2.8	mΩ
RDS(ON)	Drain-Source On-State Resistance	V <sub>GS</sub> =4.5V, I <sub>D</sub> =15A T <sub>J</sub> =25℃		3.4	4.5	mΩ
Dynamic Chara	octeristics			•		•
Ciss	Input Capacitance			4070		pF
Coss	Output Capacitance	V <sub>DS</sub> =15V,V <sub>GS</sub> =0V, f=1.0MHz		407		pF
Crss	Reverse Transfer Capacitance			368		pF
Rg	Gate resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, f=1.0MHz		1.7		Ω
Switching Para	meters					
t <sub>d(on)</sub>	Turn-on Delay Time			10		nS
t <sub>r</sub>	Turn-on Rise Time	V <sub>GS</sub> =10V, V <sub>DS</sub> =15V,		15		nS
$t_{\sf d(off)}$	Turn-Off Delay Time	$R_L$ =0.75Ω, $R_{GEN}$ =3Ω		40		nS
t <sub>f</sub>	Turn-Off Fall Time			12		nS
Qg	Total Gate Charge			68		nC
Qgs	Gate-Source Charge	V <sub>GS</sub> =10V, V <sub>DS</sub> =15V, I <sub>D</sub> =20A		17		nC
$Q_{gd}$	Gate-Drain Charge			16		nC
Source-Drain D	liode Characteristics			•		•
I <sub>SD</sub>	Source-Drain Current (Body Diode)				155	Α
V <sub>SD</sub>	Forward on Voltage (Note 3)	V <sub>GS</sub> =0V, I <sub>S</sub> =20A			1.2	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> =20A, dI/dt=100A/μs		18		ns
Qrr	Reverse Recovery Charge	I <sub>F</sub> =20A, dI/dt=100A/μs		6		nC

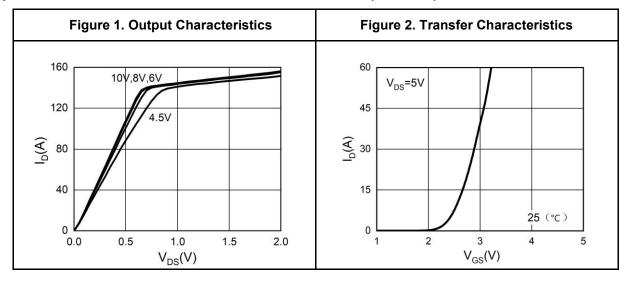
Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature.

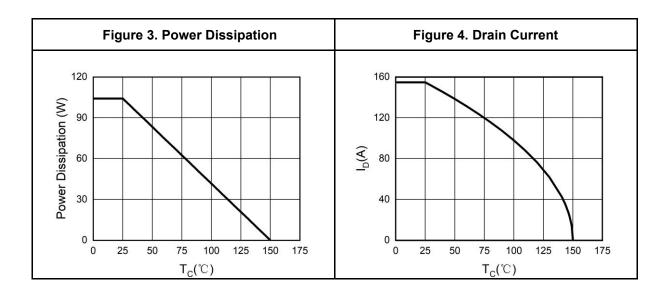
Notes 2.E<sub>AS</sub> condition:  $T_J=25^{\circ}C$ ,  $V_{DD}=30V$ ,  $V_G=10V$ ,  $Rg=25\Omega$ , L=0.5mH.

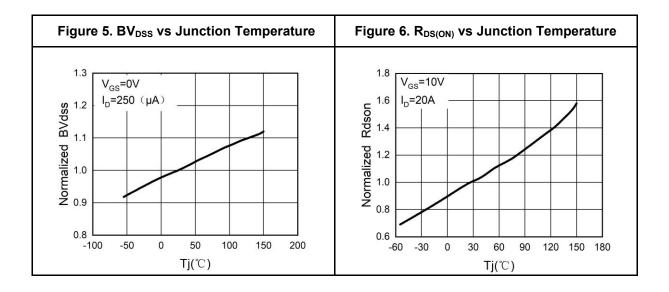
Notes 3.Repetitive Rating: Pulse width limited by maximum junction temperature.



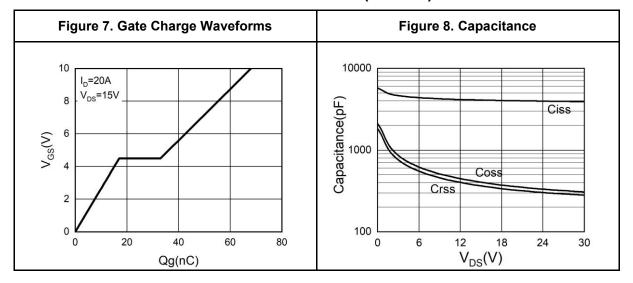
# **Typical Electrical And Thermal Characteristics (Curves)**

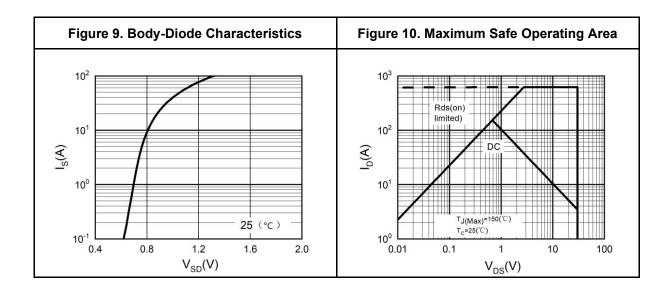






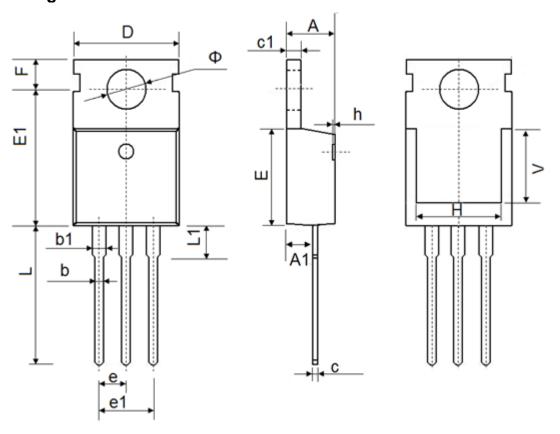
# **Typical Electrical And Thermal Characteristics (Curves)**







# **TO-220 Package Information**



Symbol	Dimen	sions In Millimeters	Dim	ensions In Inches
Symbol	Min.	Max.	Min.	Max
Α	4.300	4.700	0.169	0.185
A1	2.200	2.600	0.087	0.102
b	0.700	0.950	0.028	0.037
b1	1.170	1.410	0.046	0.056
С	0.450	0.650	0.018	0.026
c1	1.200	1.400	0.047	0.055
D	9.600	10.400	0.378	0.409
E	8.8500	9.750	0.348	0.384
E1	12.650	12.950	0.498	0.510
е	2.540 TYP.		0.100TYP.	
e1	4.980	5.180	0.196	0.204
F	2.650	2.950	0.104	0.116
Н	7.900	8.100	0.311	0.319
h	0.000	0.300	0.000	0.012
L	12.750	14.300	0.502	0.563
L1	2.850	3.950	0.112	0.156
V	7.500 REF.		0.295 REF.	
Ф	3.400	4.000	0.134	0.157

#### **Attention**

This product described in this document can not be used in life support devices or systems, aircraft's control systems, and other applications whose failure can be reasonably expected to result in serious physical and/or material damage, apart from that when an application agreement is signed between customer and Wuxi Shangjia Semiconductor

The performances and characteristics of this product in the independent testing state are displayed in this document. Wuxi Shangjia Semiconductor can't guarantee of the performances and characteristics of this described product that mounted in the customer's products or equipments as same as that in the independent testing state. So the customer should evaluate and test devices mounted in the customer's products or equipments.

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